

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Terunao HANOAKA et al.

Group Art Unit: 2826

Application No.: 09/700,464

Examiner:

L. Andujar

Filed: November 15, 2000

Docket No.:

107284

For:

SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURE THEREOF,

CIRCUIT BOARD, AND ELECTRONIC INSTRUMENT

## AMENDMENT UNDER 37 C.F.R. §1.111

Director of the U.S. Patent and Trademark Office Washington, D.C. 20231

Sir:

or of the U.S. Patent and Trademark Office
Ington, D.C. 20231

In reply to the August 30, 2002 Office Action, please amend the above-identified

00000005 150461 09700464 12/24/2002 SDAVIS application as follows: 01 FC:1202

## IN THE CLAIMS:

Please cancel claim 18 without prejudice or disclaimer.

Please replace rewritten claims 1, 10, 13, 21, 22, 23 and 24 as follows:

(Amended) A semiconductor device comprising: 1.

a semiconductor element having a plurality of electrodes;

an interconnect pattern electrically connected to the electrodes;

external terminals electrically connected to the interconnect pattern; and

a plurality of insulating layers formed around the external terminals on the interconnect pattern, the insulating layers made of resin, the insulating layers respectively

having holes formed therein to form an opening portion, each of the external terminals

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